

Abstract

A semiconductor packaging method, includes: fixing a first die, a second die and a conductive post to a carrier board, the first die provided on a back side thereof with an inductance element, the conductive post disposed between the first and second dies; forming a plastic encapsulation layer on the carrier board, the plastic encapsulation layer encapsulating the first die, the second die, the inductance element and the conductive post, a first electrical connection point of the inductance element and one end of the conductive post being both exposed from the plastic encapsulation layer; forming a first conductive trace on a first surface of the plastic encapsulation layer, the first conductive trace connecting the first electrical connection point of the inductance element to the first end of the conductive post, the first surface of the plastic encapsulation layer representing its surface that is disposed closer to the back side of the first die than to a front side of the first die; removing the carrier board; and forming a second conductive trace on a second surface of the plastic encapsulation layer, the second conductive trace connecting a second bond pad on the second die to a second end of the conductive post, the second surface of the plastic encapsulation layer opposing the first surface thereof. Also disclosed is a semiconductor package structure.